

650V 50A Trench and Field Stop IGBT

DESCRIPTION:

- · High ruggedness performance
- · Easy parallel switching capability
- High efficiency for inverters.
- · RoHS compliant.

TYPICAL APPLICATIONS:

- PFC appliances
- Welding machines



TO-247

IGBT

MAXIMUM RATINGS (Tvj=25°C unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Collector-Emitter Voltage		V _{CES}	650	٧
Continuous collector current	Tc=25°C Tc=100°C	I _{C nom}	100 50	Α
Pulsed collector current	t _P limited by Tvjmax	I _{CM}	200	Α
Gate emitter voltage		V _{GE}	±20	V
Power dissipation	Tc=25°C Tc=100°C	P tot	312 156	W
Temperature under switching conditions		Tvj op	-40~+175	$^{\circ}\!\mathbb{C}$
Storage temperature		T _{STG}	-55~+150	$^{\circ}\!\mathbb{C}$

THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Max.	Unit
IGBT thermal resistance, junction - case		R _{th(j-C)}	0.48	K/W
Diode thermal resistance, junction - case		R _{th(j-C)}	0.90	K/W
Thermal resistance, junction - ambient		R _{th(j-A)}	40	K/W

ELECTRICAL CHARATERISTICS

ELECTRICAL CHARATERISTICS Characteristic	Symbol	Min.	Тур.	Max.	Unit
Collector-emitter cut-off current VCE=650V, VGE=0V Tvj=25°C	I _{CES}			50	uA
Gate-emitter leakage current VCE=0V, VGE=20V Tvj=25°C	I _{GES}			100	nA
Gate-Emitter threshold voltage IC=1.0mA, VGE= VCE Tvj=25°C	$V_{GE(th)}$	5.0	5.4	5.6	V
Collector-Emitter saturation voltage VGE=15V, IC=50A Tvj=25°C VGE=15V, IC=50A Tvj=175°C	$V_{\text{CE(SAT)}}$		1.9 2.6		V
Input capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25℃	C _{ies}		4820		pF
Output capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25℃	C _{oes}		136		pF
Reverse transfer capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25℃	C _{res}		37		pF
Gate charge IC = 50A, VGE = 15 V,VCC =520V Tvj=25°C	Q_{G}		158		nC
Turn-on delay time IC=50A, VCC=400 V	td _(ON)		50 46		ns
Rise time IC=50A, VCC=400 V Tvj=25 $^{\circ}$ C VGE=0/15 V, RG=10 Ω Tvj=175 $^{\circ}$ C (inductive load)	tr		81 83		ns
Turn-off delay time IC=50A, VCC=400 V	td _(OFF)		190 205		ns
Fall time IC=50A, VCC=400 V Tvj=25 $^{\circ}$ C VGE=0/15 V, RG=10 $^{\circ}$ Tvj=175 $^{\circ}$ C (inductive load)	tf		59 66		ns
Turn-on energy IC=50A, VCC=400 V Tvj=25 $^{\circ}$ C VGE=0/15 V, RG=10 Ω Tvj=175 $^{\circ}$ C (inductive load)	E _(ON)		1.7 2.5		mJ
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Turn-off energy loss per pulse IC=50A, VCC=400 V	E _(OFF)		0.9 1.0		mJ	
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Diode

MAXIMUM RATINGS (Tvj=25 $^{\circ}$ C unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Repetitive peak reverse voltage	Tvj=25℃	V_{RRM}	650	V
Continuous forward current	Tc=100°C	I _F	50	Α
Diode maximum current	t _P limited by Tvj max	I _{FM}	200	Α

ELECTRICAL CHARATERISTICS

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Forward voltage IF=50A, VGE=0 V Tvj=25°C IF=50A, VGE=0 V Tvj=175°C	V _F		2.5 2.0		V
Reverse Recovered Time IF=50 A, Tvj=25°C -diF/dt =800A/µs Tvj=175°C VR=400 V	T _{rr}		75 114		ns
Peak reverse recovery current IF=50 A, Tvj=25°C -diF/dt =800A/µs Tvj=175°C VR=400 V	I _{RRM}		14 22		А
Reverse Recovered charge IF=50 A, Tvj=25°C -diF/dt =800A/μs Tvj=175°C VR=400 V	Q _{rr}		482 1384		nC

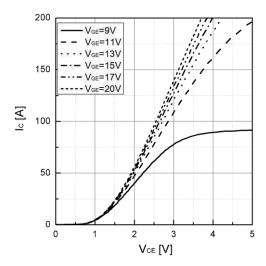


Figure 1. Typical output characteristics (Tvj=25 $^{\circ}$ C)

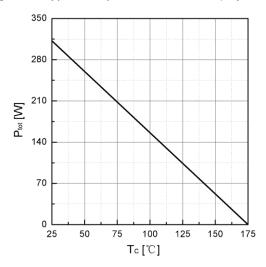


Figure 3. Power dissipation as a function of TC

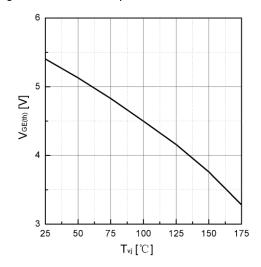


Figure 5. Typical VGE(th) as a function of Tvj $(I_C=1mA)$

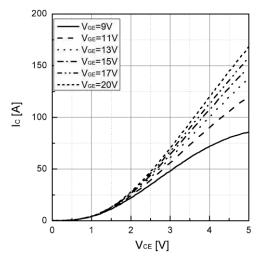


Figure 2. Typical output characteristics (Tvj=175°C)

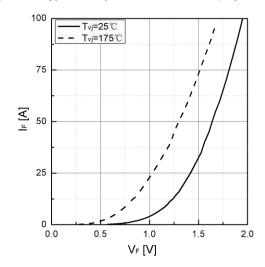


Figure 4. Typical IF as a function of VF

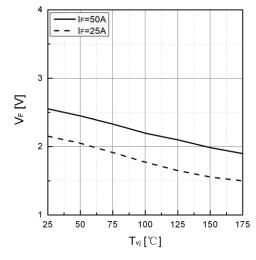


Figure 6. Typical VF as a function of Tvj

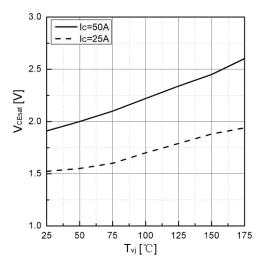


Figure 7. Typical VCEsat as a function of Tvj

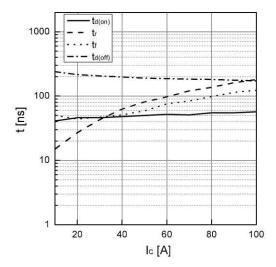


Figure 9. Typical switching times as a function of IC

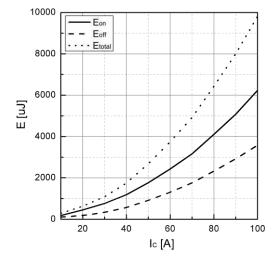


Figure 11. Typical switching energy losses as a function of IC

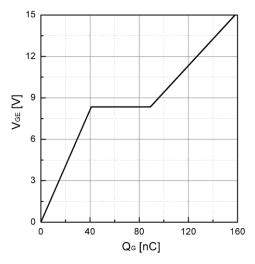


Figure 8. Typical Gate charge

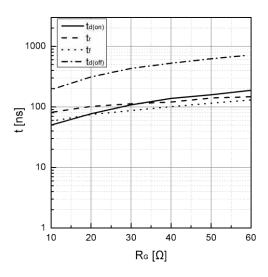


Figure 10. Typical switching times as a function of RG

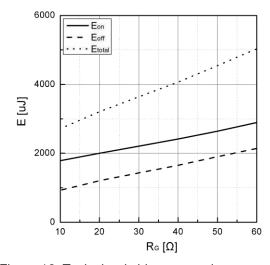


Figure 12. Typical switching energy losses as a function of RG

RA-D-1654 Ver.A

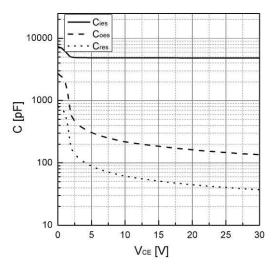


Figure 13. Typical capacitance as a function of VCE (f=1Mhz, VGE=0V)

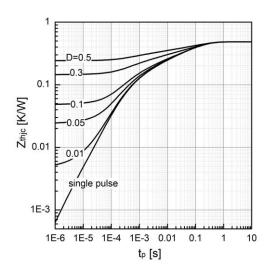
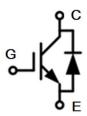
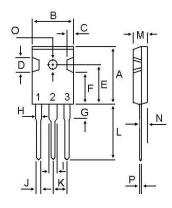


Figure 14. Transient thermal impedance, IGBT

· Circuit diagram



• Package outlines : Dimensions in (mm)



DIM	MILLIMETERS		
DIW	MIN	MAX	
Α	20.80	21.80	
В	15.38	16.20	
С	1.90	2.70	
D	5.10	6.10	
Е	14.50	15.50	
F	11.20	13.20	
G	3.75	4.35	
Н	1.90	2.30	
- 1	2.90	3.30	
J	1.00	1.40	
K	5.26	5.66	
L	19.50	20.50	
M	4.68	5.36	
N	2.30	2.60	
0	3.45	3.85	
Р	0.48	0.72	



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